

## REMARKS

## CLAIM OBJECTIONS

- 5 Claim 2 has been amended to overcome the objection.

## CLAIM REJECTIONS UNDER 35 USC 102

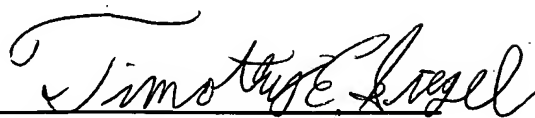
- 10 With respect to claims 13 and 14, applicant submits that  
reference number 306 of FIG. 3B of Lin does not show a  
trench, as posited by the PTO, but rather a via, as  
stated in the text of Lin. Accordingly, the result is not  
a "vertical planar conductive feature" (emphasis added)  
as recited in paragraph (b) of claim 13, but rather a  
15 plated via, something already common in the art. This is  
an important distinction, because a vertical planar  
conductive feature can serve a connective function  
between features on different levels of a multilevel  
circuit, in a manner that can not be achieved by  
20 currently available technology, which includes the use of  
plated vias. For example, in some instances insufficient  
real estate is available to route a trace having  
horizontal width, but a vertical trace (i.e. a vertical  
planar conductive feature) could be used. Claim 14 is  
25 patentably distinct over the prior art because it depends  
on claim 13, which is patentably distinct over the prior  
art.

It is respectfully submitted that the claims are now  
in condition for allowance. Reconsideration and early  
notice of allowance are respectfully solicited.

5

Respectfully submitted,

10



Timothy E. Siegel  
Attorney for Applicant  
Reg. No.: 37,442  
Tel. No.: (503) 650-7411  
Fax No.: (503) 650-9886

15

20

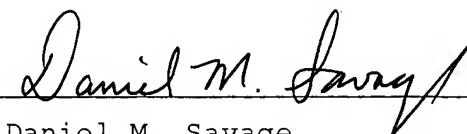
CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first  
class mail in an envelope addressed to:

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

on May 5, 2005

Signed: \_\_\_\_\_



Date: 05/05/2005

35

Daniel M. Savage